# AMPMODU | AMPMODU Headers

TE Internal #: 4-146495-0

PCB Mount Header, Vertical, Board-to-Board, 80 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal,

AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: **80**Number of Rows: **2** 

# **Features**

# **Product Type Features**

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Unshrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

# **Configuration Features**

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	80
Number of Rows	2
Board-to-Board Configuration	Parallel

#### **Electrical Characteristics**

Insulation Resistance	5000 MΩ	

# **Body Features**

Primary Product Color	Black	
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#### **Contact Features**

Contact Mating Area Length	8.38 mm[.33 in]
Mating Square Post Dimension	.64 mm[.025 in]



	15 μin
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	8.38 mm[.33 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
	2.54 mm[.1 in] Thermoplastic
Centerline (Pitch)	
Centerline (Pitch)  Housing Material	
Centerline (Pitch)  Housing Material  Dimensions	Thermoplastic
Centerline (Pitch)  Housing Material  Dimensions  Row-to-Row Spacing	Thermoplastic  2.54 mm[.1 in]
Centerline (Pitch)  Housing Material  Dimensions  Row-to-Row Spacing  Stack Height	Thermoplastic  2.54 mm[.1 in]  6.86 mm[.27 in]
Centerline (Pitch)  Housing Material  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)	Thermoplastic  2.54 mm[.1 in]  6.86 mm[.27 in]
Centerline (Pitch)  Housing Material  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)  Usage Conditions	Thermoplastic  2.54 mm[.1 in]  6.86 mm[.27 in]  1.4 mm[.055 in]
Centerline (Pitch)  Housing Material  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)  Usage Conditions  Operating Temperature Range	Thermoplastic  2.54 mm[.1 in]  6.86 mm[.27 in]  1.4 mm[.055 in]
Centerline (Pitch)  Housing Material  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)  Usage Conditions  Operating Temperature Range  Operation/Application	Thermoplastic  2.54 mm[.1 in]  6.86 mm[.27 in]  1.4 mm[.055 in]  -65 – 125 °C[-85 – 257 °F]
Centerline (Pitch) Housing Material  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)  Usage Conditions  Operating Temperature Range  Operation/Application  Assembly Process Feature	Thermoplastic  2.54 mm[.1 in]  6.86 mm[.27 in]  1.4 mm[.055 in]  -65 – 125 °C[-85 – 257 °F]  None
Centerline (Pitch)  Housing Material  Dimensions  Row-to-Row Spacing  Stack Height  PCB Thickness (Recommended)  Usage Conditions  Operating Temperature Range  Operation/Application  Assembly Process Feature  Circuit Application	Thermoplastic  2.54 mm[.1 in]  6.86 mm[.27 in]  1.4 mm[.055 in]  -65 – 125 °C[-85 – 257 °F]  None



#### **Packaging Features**

Packaging Quantity	75
Packaging Type	Carton

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts





Also in the Series | AMPMODU Headers





PCB Connector Mounting(1)



PCB Connector Shrouds(1)



PCB Headers & Receptacles(4875)



PCB Latches, Locks & Retainers(1)



Wire-to-Board Connector Assemblies & Housings(5)



Wire-to-Board Connector Contacts(65)

# Customers Also Bought



TE Part #3-6318491-6 .5FHP08H,220,S,GIG,08/Sn,HT,NSYes



TE Part #1-1571983-4
GDH10STR04=DIP SWITCH



TE Part #5-146282-4
04 MODII HDR SRST B/A .100CL



TE Part #9-1879131-3 RN 0402 12K1 0.1% 10PPM 5K RL



TE Part #2842143-4 8P,2MM,BRK HDR,DRVT,SMD,0.38AU, TR W/CAP



TE Part #1-2176337-4 CRGCQ 0402 120R 1%



TE Part #2-2308107-0
DDR4 DIMM 288 PIN TH TYPE





TE Part #5-2349820-3 PCIEG4,SMT,V,98P,30u,ML,HT,OEW

TE Part #1-2314678-1 NON-FABRIC PHLM KIT, LGA3647, W/ COVER

# **Documents**

PCB Mount Header, Vertical, Board-to-Board, 80 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal, AMPMODU Headers



**Product Drawings** 

80 MODII HDR DRST UNSHRD STKG

English

Datasheets & Catalog Pages

AMPMODU Interconnetion System

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English